



Features

- DC – 3.0 GHz
- 25 Watts
- Aluminum Nitride (AlN) Ceramic
- Surface Mountable
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

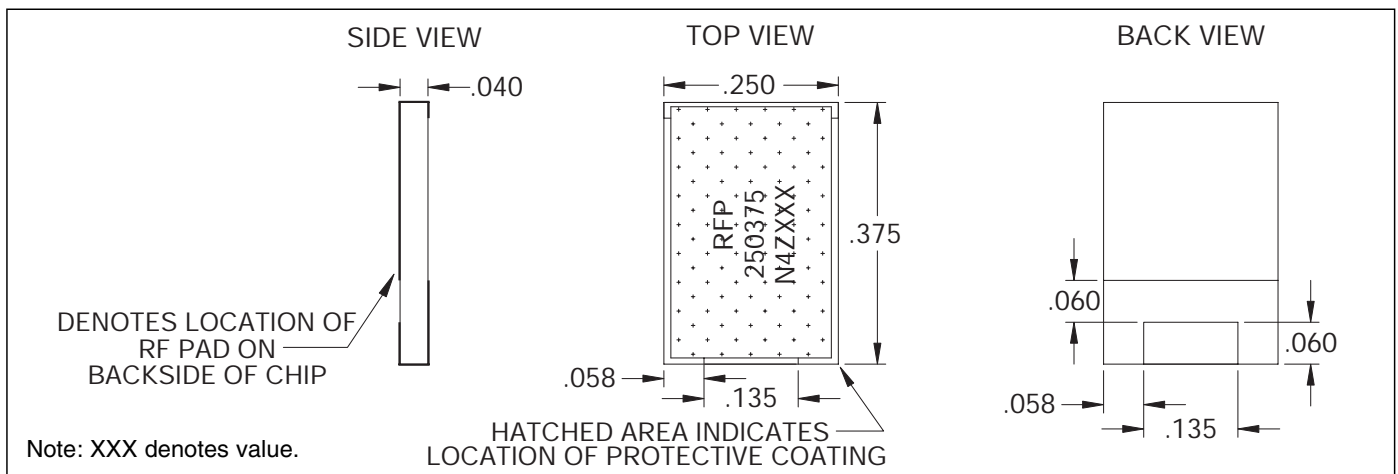
Resistive Element:	Thick film
Substrate:	Aluminum nitride ceramic
Terminals:	Tin/Lead, 90/10 over nickel

Electrical Specifications

Resistance Value:	50 ohms, ±2%
Frequency Range:	DC - 3.0 GHz
Power:	25 Watts
V.S.W.R.:	1.25:1

Notes: Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +125°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches.
Specifications subject to change without notice.

Outline Drawing



Available on Tape and Reel for Pick and Place Manufacturing.

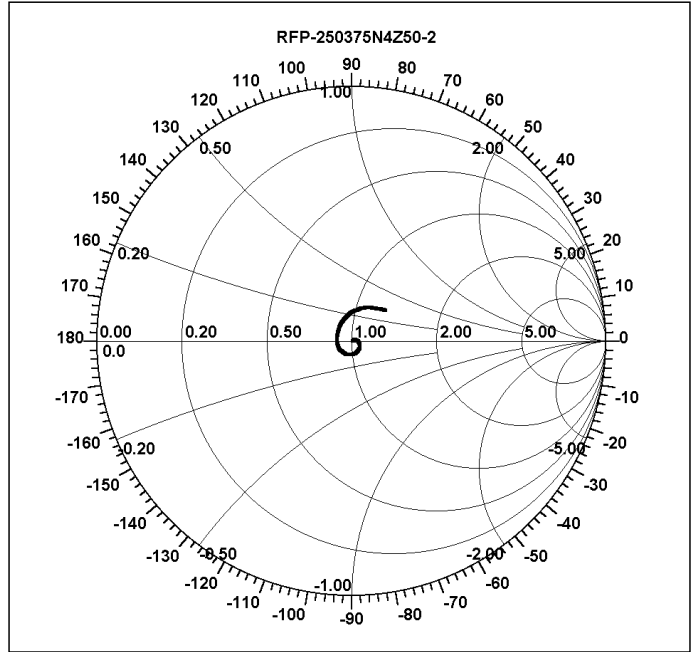
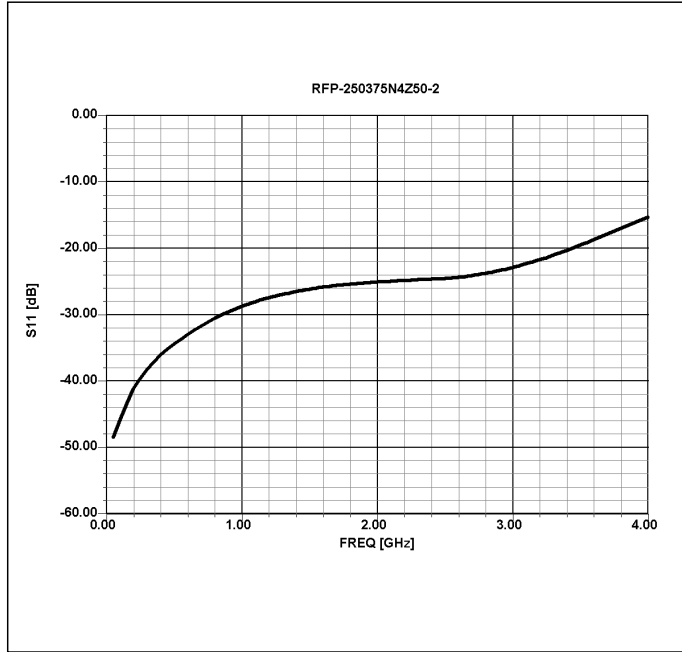
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Model RFP-250375N4Z50-2

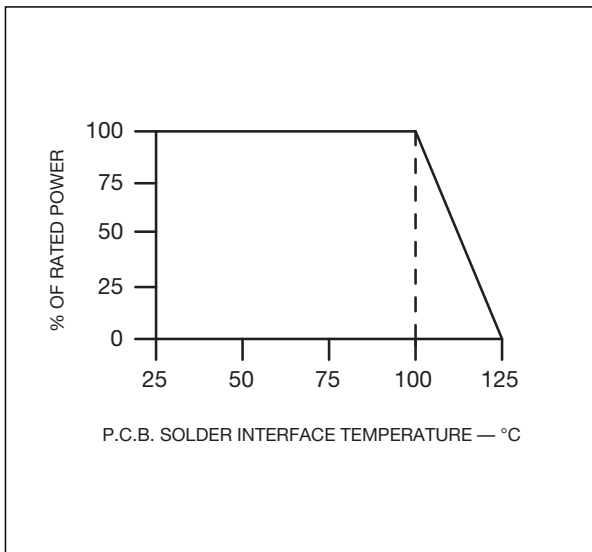


RF Power

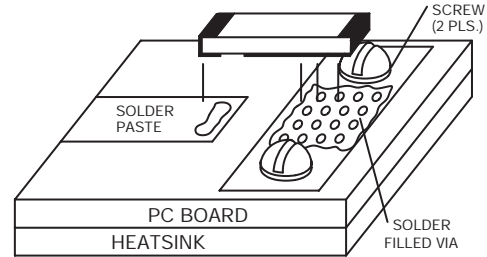
Typical Performance



Power Derating



Suggested Mounting Procedures



1. Solder part in place using 60/40 type solder with controlled temperature iron (700°F).
2. Drill thermal via through PCB and fill with solder, such as 60/40 type.
3. To ensure good thermal connectivity to heat sink, drill and tap heatsink and mount PCB board to heat sink using screws.

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